

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/17/10546	
<b>1.3 Title of PCN</b>	ASE Kaohsiung (Taiwan) additional source for LQFP 7x7 STM32F0-F1-F3 listed products	
<b>1.4 Product Category</b>	LQFP 7x7 STM32F0-F1-F3 listed products	
<b>1.5 Issue date</b>	2017-12-21	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	MARSHALL DAVE
<b>2.1.2 Phone</b>	
<b>2.1.3 Email</b>	dave.marshall@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Michel BUFFA
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung (Taiwan)

**4. Description of change**

	Old	New
<b>4.1 Description</b>	Back-end sources: - Stats ChipPAC Jiangyin China (JSCC) - ST Muar Malaysia - Amkor ATP Philippines	Back-end sources: - Stats ChipPAC Jiangyin China (JSCC) - ST Muar Malaysia - Amkor ATP Philippines - ASE Kaohsiung Taiwan - Additional source For more information, please refer to PCN 10546 – Additional information attached document.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	Lead color and surface finish change depending on leadfinishing. Package darkness changes depending on molding compound.	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Change is visible through assembly traceability plant, in the marking: - "GQ" and "GH" for Stats ChipPAC China - "9H" for ST Muar Malaysia - "7B" for Amkor Philippines - "AA" for ASE Kaohsiung Taiwan Please refer to PCN 10546 – Additional information attached document.
------------------------	--

**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2018-03-30
<b>7.2 Intended start of delivery</b>	2018-03-30
<b>7.3 Qualification sample available?</b>	Upon Request

8. Qualification / Validation			
-------------------------------	--	--	--

<b>8.1 Description</b>	10546 MDG-MCD-RER1717 PCN10546 ASEKH_LQFP 7x7 STM32F0_F1_F3 reliability plan.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2017-12-21

9. Attachments (additional documentations)			
--	--	--	--

10546 Public product.pdf 10546 MDG-MCD-RER1717 PCN10546 ASEKH_LQFP 7x7 STM32F0_F1_F3 reliability plan.pdf 10546 PCN10546_Additional information.pdf			
---	--	--	--

10. Affected parts		
--------------------	--	--

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F091CBT6	

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics – All rights reserved